



TPS6040x Unregulated 60-mA Charge Pump Voltage Inverter

1 Features

- Inverts Input Supply Voltage
- Up to 60-mA Output Current
- Only Three Small 1- μ F Ceramic Capacitors Needed
- Input Voltage Range From 1.6 V to 5.5 V
- PowerSave-Mode for Improved Efficiency at Low-Output Currents (TPS60400)
- Device Quiescent Current Typical 65 μ A
- Integrated Active Schottky-Diode for Start-up Into Load
- Small 5-Pin SOT-23 Package
- Evaluation Module Available TPS60400EVM-178

2 Applications

- LCD Bias
- GaAs Bias for RF Power Amps
- Sensor Supply in Portable Instruments
- Bipolar Amplifier Supply
- Medical Instruments
- Battery-Operated Equipment

3 Description

The TPS6040x family of devices generates an unregulated negative output voltage from an input voltage ranging from 1.6 V to 5.5 V. The devices are typically supplied by a preregulated supply rail of 5 V or 3.3 V. Due to its wide input voltage range, two or three NiCd, NiMH, or alkaline battery cells, as well as one Li-Ion cell can also power them.

Only three external 1- μ F capacitors are required to build a complete DC-DC charge pump inverter. Assembled in a 5-pin SOT-23 package, the complete converter can be built on a 50-mm² board area. Additional board area and component count reduction is achieved by replacing the Schottky diode that is typically needed for start-up into load by integrated circuitry.

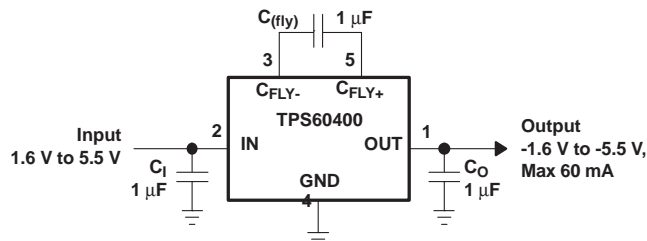
The TPS6040x can deliver a maximum output current of 60 mA with a typical conversion efficiency of greater than 90% over a wide output current range. Three device options with 20-kHz, 50-kHz, and 250-kHz fixed-frequency operation are available. TPS60400 comes with a variable switching frequency to reduce operating current in applications with a wide load range and enables the design with low-value capacitors.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|-------------------|
| TPS6040x | SOT-23 (5) | 2.90 mm x 1.60 mm |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Typical Application



Output Voltage vs Input Voltage

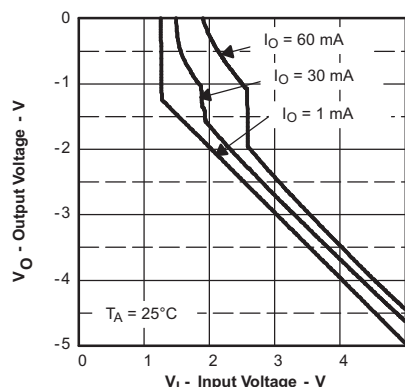


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4 Revision History

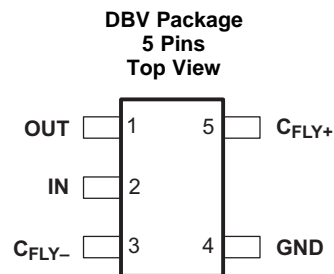
| Changes from Revision A (November 2004) to Revision B | Page |
|---|----------|
| <ul style="list-style-type: none"> Added <i>Handling Rating</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section | 1 |

5 Device Comparison Table

| PART NUMBER ⁽¹⁾ | MARKING DBV PACKAGE | TYPICAL FLYING CAPACITOR [μF] | FEATURE |
|----------------------------|---------------------|-------------------------------|---|
| TPS60400DBV | PFKI | 1 | Variable switching frequency 50 kHz-250 kHz |
| TPS60401DBV | PFLI | 10 | Fixed frequency 20 kHz |
| TPS60402DBV | PFMI | 3.3 | Fixed frequency 50 kHz |
| TPS60403DBV | PFNI | 1 | Fixed frequency 250 kHz |

(1) The DBV package is available taped and reeled. Add R suffix to device type (for example, TPS60400DBVR) to order quantities of 3000 devices per reel. Add T suffix to device type (for example, TPS60400DBVT) to order quantities of 250 devices per reel.

6 Pin Configuration and Functions



Pin Functions

| PIN | | I/O | DESCRIPTION |
|-------------------|-----|-----|--|
| NAME | NO. | | |
| C _{FLY+} | 5 | | Positive terminal of the flying capacitor C _(fly) |
| C _{FLY-} | 3 | | Negative terminal of the flying capacitor C _(fly) |
| GND | 4 | | Ground |
| IN | 2 | I | Supply input. Connect to an input supply in the 1.6-V to 5.5-V range. Bypass IN to GND with a capacitor that has the same value as the flying capacitor. |
| OUT | 1 | O | Power output with V _O = -V _I . Bypass OUT to GND with the output filter capacitor C _O . |

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|--|--------------------------|---------------------------------------|----------------------|------|
| Voltage range | IN to GND | -0.3 | 5.5 | V |
| | OUT to GND | -5.5 | 0.3 | V |
| | C _{FLY-} to GND | 0.3 | V _O - 0.3 | V |
| | C _{FLY+} to GND | -0.3 V | V _I + 0.3 | V |
| Continuous power dissipation | | See Power Dissipation | | |
| Continuous output current | | | 80 | mA |
| Maximum junction temperature, T _J | | | 150 | °C |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 Handling Ratings

| | | | MIN | MAX | UNIT |
|--------------------|---------------------------|--|-------|-------|------|
| T _{stg} | Storage temperature range | | -55°C | 150°C | °C |
| V _(ESD) | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾ | -1000 | 1000 | V |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾ | -500 | 500 | |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

| | MIN | NOM | MAX | UNIT |
|--|-----|--------------------|------|------|
| Input voltage range, V _I | 1.8 | | 5.25 | V |
| Output current range at OUT, I _O | | | 60 | mA |
| Input capacitor, C _I | 0 | C _(fly) | | μF |
| Flying capacitor, C _(fly) | | 1 | | μF |
| Output capacitor, C _O | | 1 | 100 | μF |
| Operating junction temperature, T _J | -40 | | 125 | °C |

7.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | TPS6040x | UNIT |
|-------------------------------|--|----------|------|
| | | DBV | |
| | | 5 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 221.2 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 81.9 | |
| R _{θJB} | Junction-to-board thermal resistance | 39.8 | |
| Ψ _{JT} | Junction-to-top characterization parameter | 3.3 | |
| Ψ _{JB} | Junction-to-board characterization parameter | 38.9 | |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | n/a | |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics

C_I = C_(fly) = C_O (according to Table 1), T_C = -40°C to 85°C, V_I = 5 V over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|------------------|--|--|-----------------------|--|----------------|------|-------------------|
| V _I | Supply voltage range | At T _C = -40°C to 85°C, R _L = 5 kΩ | | 1.8 | | 5.25 | V |
| | | At T _C ≥ 0°C, R _L = 5 kΩ | | 1.6 | | | |
| I _O | Maximum output current at V _O | | | 60 | | | mA |
| V _O | Output voltage | | | | V _I | | V |
| V _{P-P} | Output voltage ripple | TPS60400 | I _O = 5 mA | C _(fly) = 1 μF, C _O = 2.2 μF | | 35 | mV _{P-P} |
| | | TPS60401 | | C _(fly) = C _O = 10 μF | | 20 | |
| | | TPS60402 | | C _(fly) = C _O = 3.3 μF | | 20 | |
| | | TPS60403 | | C _(fly) = C _O = 1 μF | | 15 | |

Electrical Characteristics (continued)

$C_I = C_{(fly)} = C_O$ (according to Table 1), $T_C = -40^{\circ}\text{C}$ to 85°C , $V_I = 5\text{ V}$ over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|------------------|---|-----------------|---|-----|--------|------|-----|
| I _Q | Quiescent current (no-load input current) | TPS60400 | At V _I = 5 V | 125 | 270 | μA | |
| | | TPS60401 | | 65 | 190 | | |
| | | TPS60402 | | 120 | 270 | | |
| | | TPS60403 | | 425 | 700 | | |
| | | TPS60400 | At T ≤ 60°C, V _I = 5 V | 210 | μA | | |
| | | TPS60401 | | 135 | | | |
| | | TPS60402 | | 210 | | | |
| | | TPS60403 | | 640 | | | |
| f _{OSC} | Internal switching frequency | TPS60400 | VCO version | 30 | 50-250 | 350 | kHz |
| | | TPS60401 | | 13 | 20 | 28 | |
| | | TPS60402 | | 30 | 50 | 70 | |
| | | TPS60403 | | 150 | 250 | 300 | |
| | Impedance at 25°C, V _I = 5 V | TPS60400 | C _I = C _(fly) = C _O = 1 μF | 12 | 15 | Ω | |
| | | TPS60401 | C _I = C _(fly) = C _O = 10 μF | 12 | 15 | | |
| | | TPS60402 | C _I = C _(fly) = C _O = 3.3 μF | 12 | 15 | | |
| | | TPS60403 | C _I = C _(fly) = C _O = 1 μF | 12 | 15 | | |

7.6 Typical Characteristics

Table 1. Table of Graphs

| | | | FIGURE |
|------------------|----------------------|---|---|
| η | Efficiency | vs Output current at 3.3 V, 5 V TPS60400, TPS60401, TPS60402, TPS60403 | Figure 1, Figure 2 |
| I_I | Input current | vs Output current TPS60400, TPS60401, TPS60402, TPS60403 | Figure 3, Figure 4 |
| I_S | Supply current | vs Input voltage TPS60400, TPS60401, TPS60402, TPS60403 | Figure 5, Figure 6 |
| | Output resistance | vs Input voltage at -40°C , 0°C , 25°C , 85°C TPS60400, $C_I = C_{(fly)} = C_O = 1\text{ }\mu\text{F}$ TPS60401, $C_I = C_{(fly)} = C_O = 10\text{ }\mu\text{F}$ TPS60402, $C_I = C_{(fly)} = C_O = 3.3\text{ }\mu\text{F}$ TPS60403, $C_I = C_{(fly)} = C_O = 1\text{ }\mu\text{F}$ | Figure 7, Figure 8, Figure 9, Figure 10 |
| V_O | Output voltage | vs Output current at 25°C , $V_{IN}=1.8\text{ V}$, 2.5 V , 3.3 V , 5 V TPS60400, $C_I = C_{(fly)} = C_O = 1\text{ }\mu\text{F}$ TPS60401, $C_I = C_{(fly)} = C_O = 10\text{ }\mu\text{F}$ TPS60402, $C_I = C_{(fly)} = C_O = 3.3\text{ }\mu\text{F}$ TPS60403, $C_I = C_{(fly)} = C_O = 1\text{ }\mu\text{F}$ | Figure 11, Figure 12, Figure 13, Figure 14 |
| f_{OSC} | Oscillator frequency | vs Temperature at $V_I = 1.8\text{ V}$, 2.5 V , 3.3 V , 5 V TPS60400, TPS60401, TPS60402, TPS60403 | Figure 15, Figure 16, Figure 17, Figure 18 |
| f_{OSC} | Oscillator frequency | vs Output current TPS60400 at 2 V , 3.3 V , 5.0 V | Figure 19 |

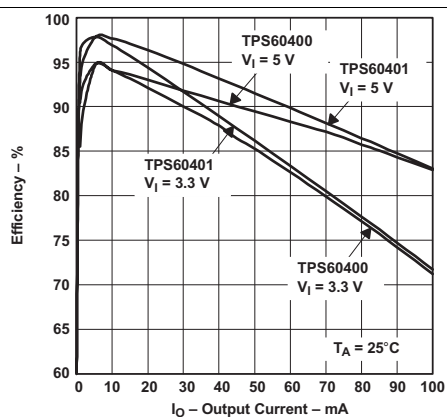


Figure 1. Efficiency vs Output Current

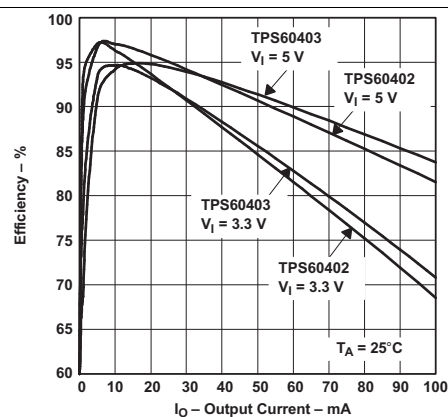


Figure 2. Efficiency vs Output Current

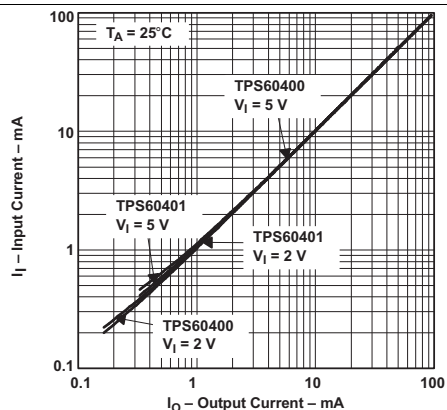


Figure 3. Input Current vs Output Current

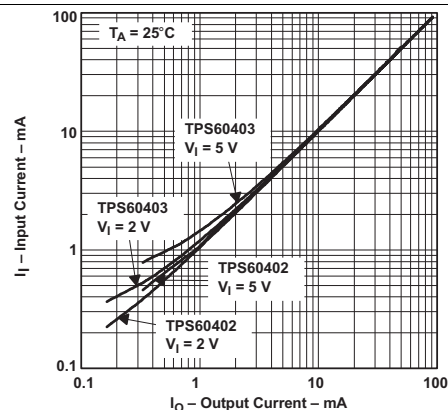


Figure 4. Input Current vs Output Current

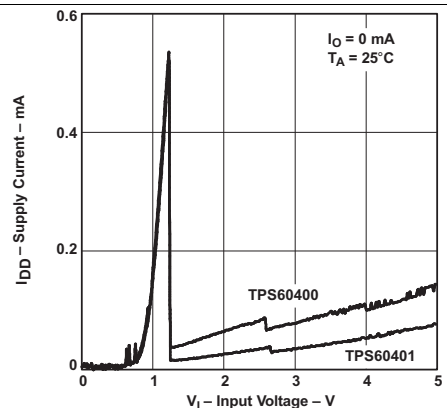


Figure 5. Supply Current vs Input Voltage

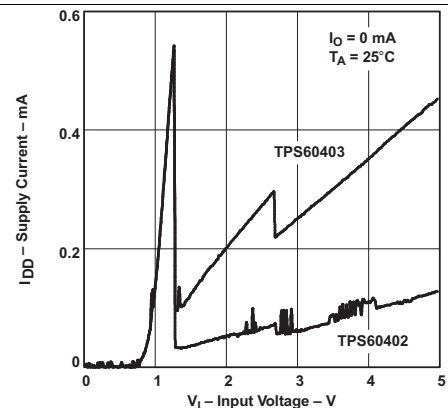


Figure 6. Supply Current vs Input Voltage

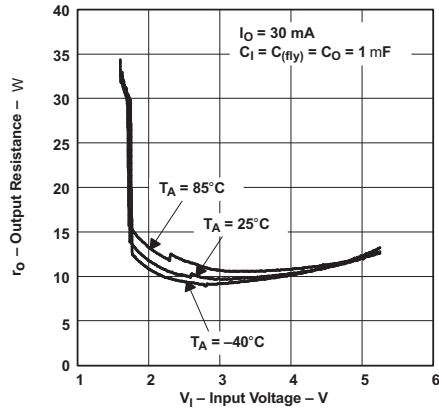


Figure 7. Output Resistance vs Input Voltage

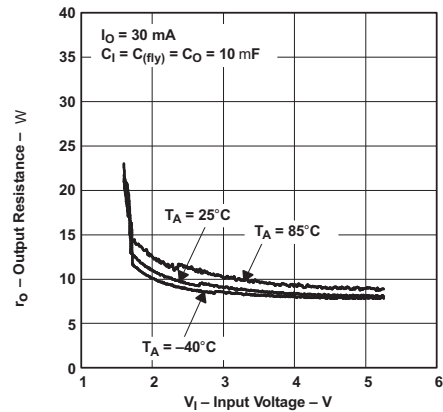


Figure 8. Output Resistance vs Input Voltage

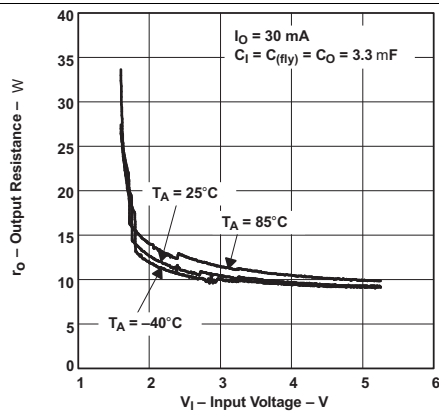


Figure 9. Output Resistance vs Input Voltage

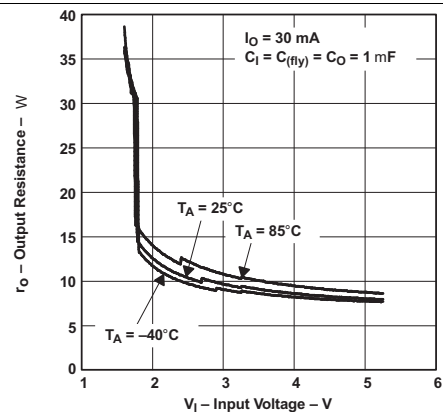


Figure 10. Output Resistance vs Input Voltage

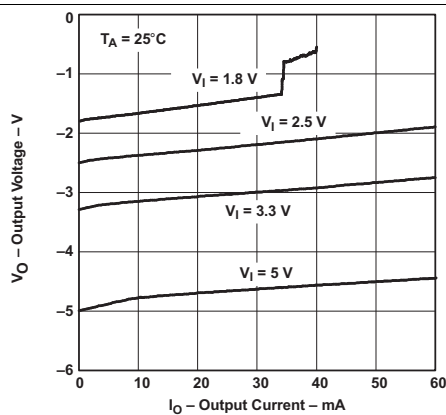


Figure 11. Output Voltage vs Output Current

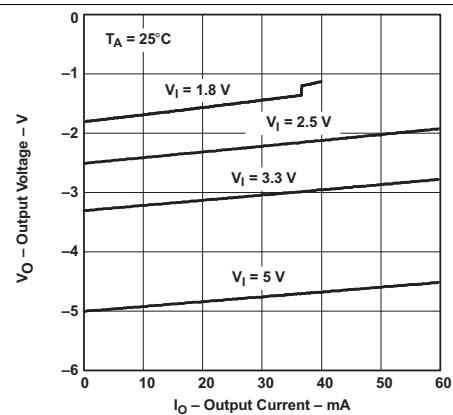


Figure 12. Output Voltage vs Output Current

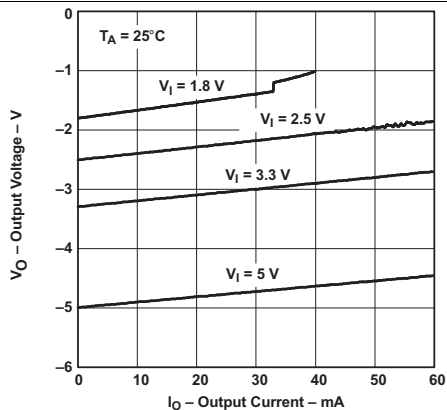


Figure 13. Output Voltage vs Output Current

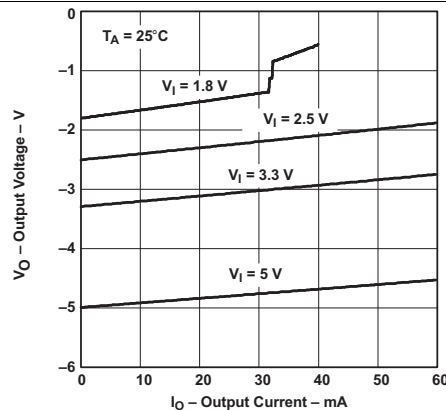


Figure 14. Output Voltage vs Output Current

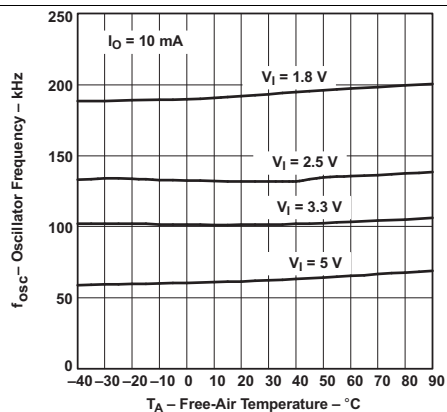


Figure 15. Oscillator Frequency vs Free-Air Temperature

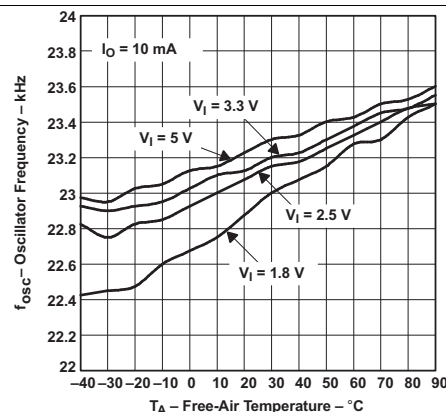


Figure 16. Oscillator Frequency vs Free-Air Temperature

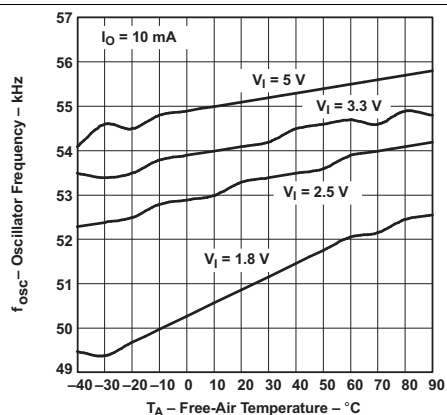


Figure 17. Oscillator Frequency vs Free-Air Temperature

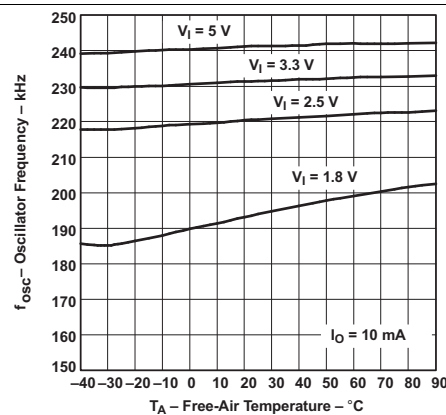


Figure 18. Oscillator Frequency vs Free-Air Temperature

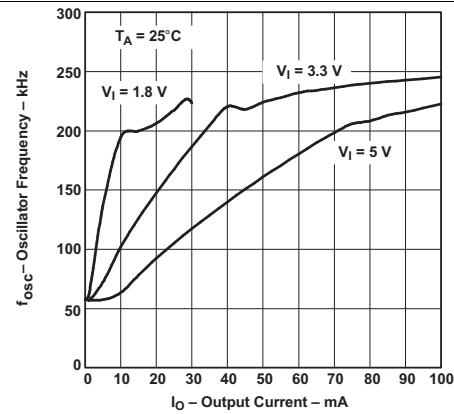


Figure 19. Oscillator Frequency vs Output Current

8 Detailed Description

8.1 Overview

The TPS60400, TPS60401 charge pumps invert the voltage applied to their input. For the highest performance, use low equivalent series resistance (ESR) capacitors (for example, ceramic). During the first half-cycle, switches S2 and S4 open, switches S1 and S3 close, and capacitor ($C_{(fly)}$) charges to the voltage at V_I . During the second half-cycle, S1 and S3 open, S2 and S4 close. This connects the positive terminal of $C_{(fly)}$ to GND and the negative to V_O . By connecting $C_{(fly)}$ in parallel, C_O is charged negative. The actual voltage at the output is more positive than $-V_I$, since switches S1-S4 have resistance and the load drains charge from C_O .

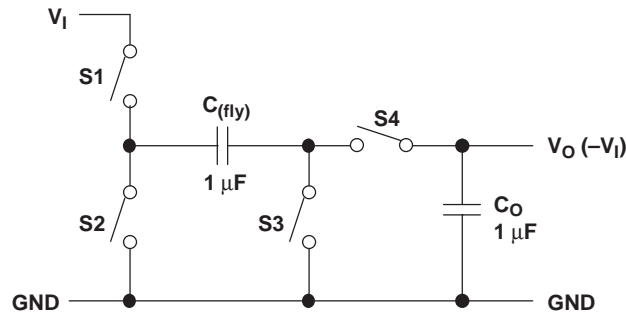
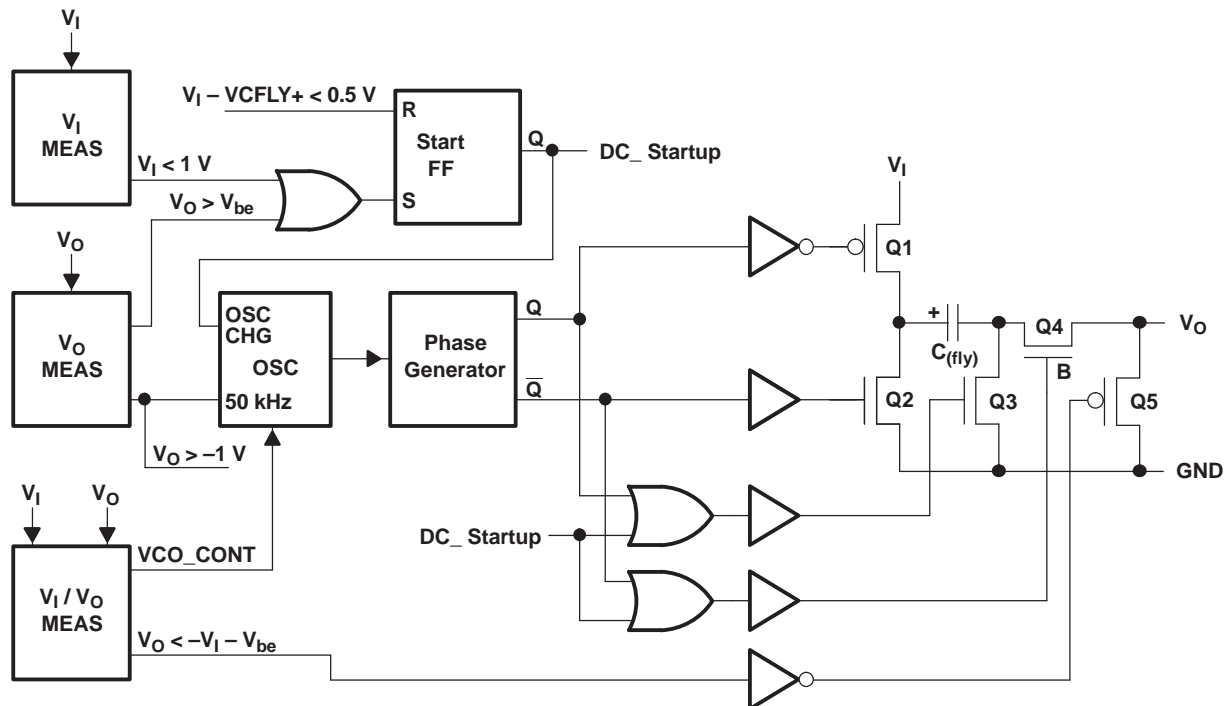


Figure 20. Operating Principle

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Charge-Pump Output Resistance

The TPS6040x devices are not voltage regulators. The charge pump's output source resistance is approximately 15 Ω at room temperature (with $V_I = 5$ V), and V_O approaches -5 V when lightly loaded. V_O droops toward GND as load current increases.

$$V_O = -(V_I - R_O \times I_O) \quad (1)$$

$$R_O \approx \frac{1}{f_{osc} \times C_{(fly)}} + 4 \left(2R_{SWITCH} + ESR_{CFLY} \right) + ESR_{CO}$$

$$R_O = \text{output resistance of the converter} \quad (2)$$

8.3.2 Efficiency Considerations

The power efficiency of a switched-capacitor voltage converter is affected by three factors: the internal losses in the converter IC, the resistive losses of the capacitors, and the conversion losses during charge transfer between the capacitors. The internal losses are associated with the internal functions of the IC, such as driving the switches, oscillator, and so forth. These losses are affected by operating conditions such as input voltage, temperature, and frequency. The next two losses are associated with the output resistance of the voltage converter circuit. Switch losses occur because of the on-resistance of the MOSFET switches in the IC. Charge-pump capacitor losses occur because of their ESR. The relationship between these losses and the output resistance is as follows:

$$P_{CAPACITOR \text{ LOSSES}} + P_{CONVERSION \text{ LOSSES}} = I_O^2 \times R_O$$

R_{SWITCH} = resistance of a single MOSFET-switch inside the converter

f_{OSC} = oscillator frequency

The first term is the effective resistance from an ideal switched-capacitor circuit. Conversion losses occur during the charge transfer between $C_{(fly)}$ and C_O when there is a voltage difference between them. The power loss is:

$$P_{CONV.LOSS} = \left[\frac{1}{2} \times C_{(fly)} (V_I^2 - V_O^2) + \frac{1}{2} C_O (V_{RIPPLE}^2 - 2V_O V_{RIPPLE}) \right] \times f_{osc} \quad (4)$$

The efficiency of the TPS6040x devices is dominated by their quiescent supply current at low output current and by their output impedance at higher current.

$$\eta \approx \frac{I_O}{I_O + I_Q} \left(1 - \frac{I_O \times R_O}{V_I} \right) \quad (5)$$

Where, I_Q = quiescent current.

8.4 Device Functional Modes

8.4.1 Active-Schottky Diode

For a short period of time, when the input voltage is applied, but the inverter is not yet working, the output capacitor is charged positive by the load. To prevent the output being pulled above GND, a Schottky diode must be added in parallel to the output. The function of this diode is integrated into the TPS6040x devices, which gives a defined startup performance and saves board space.

A current sink and a diode in series can approximate the behavior of a typical, modern operational amplifier. [Figure 21](#) shows the current into this typical load at a given voltage. The TPS6040x devices are optimized to start into these loads.

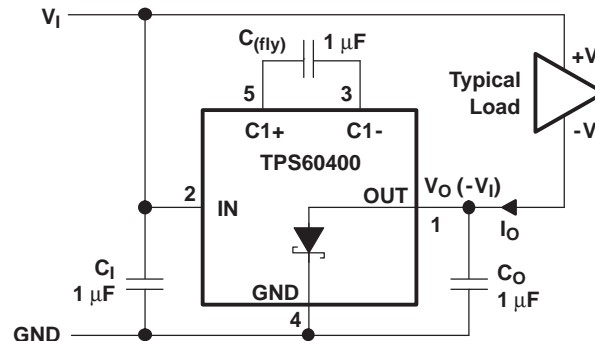


Figure 21. Typical Load

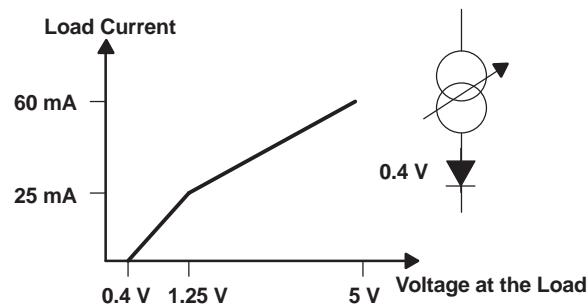


Figure 22. Maximum Start-Up Current

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The TPS6040x is a family of devices that generate an unregulated negative output voltage from an input voltage ranging from 1.6 V to 5.5 V.

9.2 Typical Application

9.2.1 Voltage Inverter

The design guidelines provide a component selection to operate the device within the recommended operating conditions.

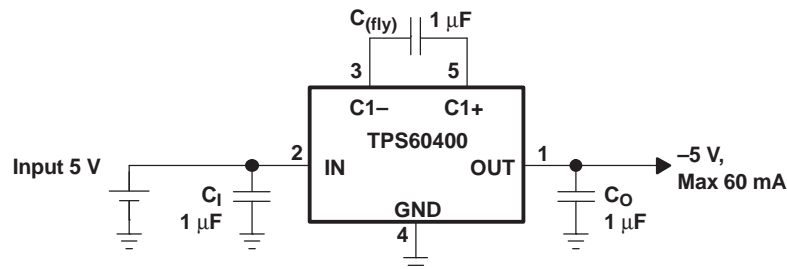


Figure 23. Typical Operating Circuit

9.2.1.1 Design Requirements

The TPS6040x is connected to generate a negative output voltage from a positive input.

9.2.1.2 Detailed Design Procedure

The most common application for these devices is a charge-pump voltage inverter (see [Figure 23](#)). This application requires only two external components; capacitors $C_{(fly)}$ and C_O , plus a bypass capacitor, if necessary. Refer to the capacitor selection section for suggested capacitor types.

For the maximum output current and best performance, three ceramic capacitors of 1 μ F (TPS60400, TPS60403) are recommended. For lower currents or higher allowed output voltage ripple, other capacitors can also be used. It is recommended that the output capacitors has a minimum value of 1 μ F. With flying capacitors lower than 1 μ F, the maximum output power decreases.

9.2.1.2.1 Capacitor Selection

To maintain the lowest output resistance, use capacitors with low ESR (see [Table 2](#)). The charge-pump output resistance is a function of $C_{(fly)}$'s and C_O 's ESR. Therefore, minimizing the charge-pump capacitor's ESR minimizes the total output resistance. The capacitor values are closely linked to the required output current and the output noise and ripple requirements. It is possible to only use 1- μ F capacitors of the same type.

9.2.1.2.2 Input Capacitor (C_I)

Bypass the incoming supply to reduce its ac impedance and the impact of the TPS6040x switching noise. The recommended bypassing depends on the circuit configuration and where the load is connected. When the inverter is loaded from OUT to GND, current from the supply switches between $2 \times I_O$ and zero. Therefore, use a large bypass capacitor (for example, equal to the value of $C_{(fly)}$) if the supply has high ac impedance. When the inverter is loaded from IN to OUT, the circuit draws $2 \times I_O$ constantly, except for short switching spikes. A 0.1- μ F bypass capacitor is sufficient.

Typical Application (continued)

9.2.1.2.3 Flying Capacitor ($C_{(fly)}$)

Increasing the flying capacitor's size reduces the output resistance. Small values increases the output resistance. Above a certain point, increasing $C_{(fly)}$'s capacitance has a negligible effect, because the output resistance becomes dominated by the internal switch resistance and capacitor ESR.

9.2.1.2.4 Output Capacitor (C_O)

Increasing the output capacitor's size reduces the output ripple voltage. Decreasing its ESR reduces both output resistance and ripple. Smaller capacitance values can be used with light loads if higher output ripple can be tolerated. Use the following equation to calculate the peak-to-peak ripple.

$$V_{O(ripple)} = \frac{I_O}{f_{osc} \times C_O} + 2 \times I_O \times ESR_{CO} \quad (6)$$

Table 2. Recommended Capacitor Values

| DEVICE | V_I [V] | I_O [mA] | C_I [μF] | $C_{(fly)}$ [μF] | C_O [μF] |
|----------|--------------|---------------|---------------|---------------------|---------------|
| TPS60400 | 1.8...5.5 | 60 | 1 | 1 | 1 |
| TPS60401 | 1.8...5.5 | 60 | 10 | 10 | 10 |
| TPS60402 | 1.8...5.5 | 60 | 3.3 | 3.3 | 3.3 |
| TPS60403 | 1.8...5.5 | 60 | 1 | 1 | 1 |

Table 3. Recommended Capacitors

| MANUFACTURER | PART NUMBER | SIZE | CAPACITANCE | TYPE |
|--------------|----------------|------|-------------|---------|
| Taiyo Yuden | EMK212BJ474MG | 0805 | 0.47 μF | Ceramic |
| | LMK212BJ105KG | 0805 | 1 μF | Ceramic |
| | LMK212BJ225MG | 0805 | 2.2 μF | Ceramic |
| | EMK316BJ225KL | 1206 | 2.2 μF | Ceramic |
| | LMK316BJ475KL | 1206 | 4.7 μF | Ceramic |
| | JMK316BJ106KL | 1206 | 10 μF | Ceramic |
| TDK | C2012X5R1C105M | 0805 | 1 μF | Ceramic |
| | C2012X5R1A225M | 0805 | 2.2 μF | Ceramic |
| | C2012X5R1A335M | 0805 | 3.3 μF | Ceramic |

Table 4 contains a list of manufacturers of the recommended capacitors. Ceramic capacitors will provide the lowest output voltage ripple because they typically have the lowest ESR-rating.

Table 4. Recommended Capacitor Manufacturers

| CAPACITOR TYPE | MANUFACTURER | WEB ADDRESS |
|-------------------|--------------|-----------------------|
| X5R / X7R ceramic | Taiyo Yuden | www.t-yuden.com |
| X5R / X7R ceramic | TDK | www.component.tdk.com |
| X5R / X7R ceramic | Vishay | www.vishay.com |
| X5R / X7R ceramic | Kemet | www.kemet.com |

9.2.1.2.5 Power Dissipation

As given in the [Thermal Information](#), the thermal resistance of TPS6040x is: $R_{\theta JA} = 221^{\circ}\text{C/W}$.

The terminal resistance can be calculated using the following equation:

$$R_{\theta JA} = \frac{T_J - T_A}{P_D} \quad (7)$$

where:

T_J is the junction temperature. T_A is the ambient temperature. P_D is the power that is dissipated by the device.

$$R_{\theta JA} = \frac{T_J - T_A}{P_D} \quad (8)$$

The maximum power dissipation can be calculated using the following equation:

$$P_D = V_I \times I_I - V_O \times I_O = V_{I(\text{max})} \times (I_O + I_{(\text{SUPPLY})}) - V_O \times I_O \quad (9)$$

The maximum power dissipation happens with maximum input voltage and maximum output current.

At maximum load the supply current is 0.7 mA maximum.

$$P_D = 5 \text{ V} \times (60 \text{ mA} + 0.7 \text{ mA}) - 4.4 \text{ V} \times 60 \text{ mA} = 40 \text{ mW} \quad (10)$$

With this maximum rating and the thermal resistance of the device on the EVM, the maximum temperature rise above ambient temperature can be calculated using the following equation:

$$\Delta T_J = R_{\theta JA} \times P_D = 221^{\circ}\text{C/W} \times 40 \text{ mW} = 8.8^{\circ}\text{C} \quad (11)$$

This means that the internal dissipation increases T_J by $<10^{\circ}\text{C}$.

The junction temperature of the device shall not exceed 125°C .

This means the IC can easily be used at ambient temperatures up to:

$$T_A = T_{J(\text{max})} - \Delta T_J = 125^{\circ}\text{C/W} - 10^{\circ}\text{C} = 115^{\circ}\text{C} \quad (12)$$

9.2.1.3 Application Curves

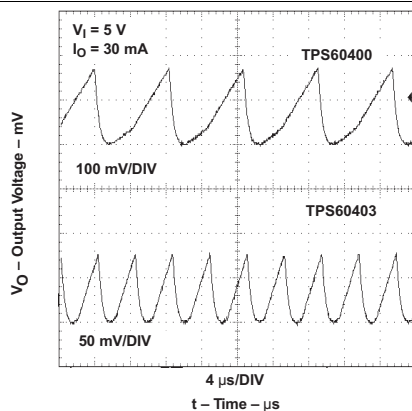


Figure 24. Output Voltage vs Time for TPS60400 and TPS60401

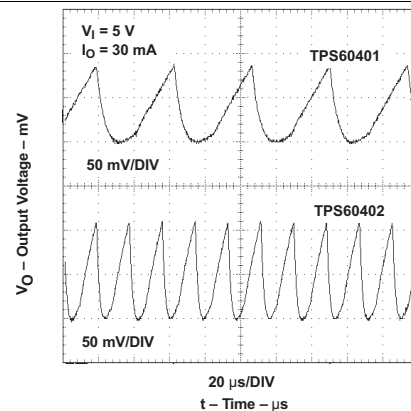


Figure 25. Output Voltage vs Time for TPS60401 and TPS60402

9.3 System Examples

To reduce the output voltage ripple, a RC post filter can be used.

An output filter can easily be formed with a resistor (R_P) and a capacitor (C_P). Cutoff frequency is given by:

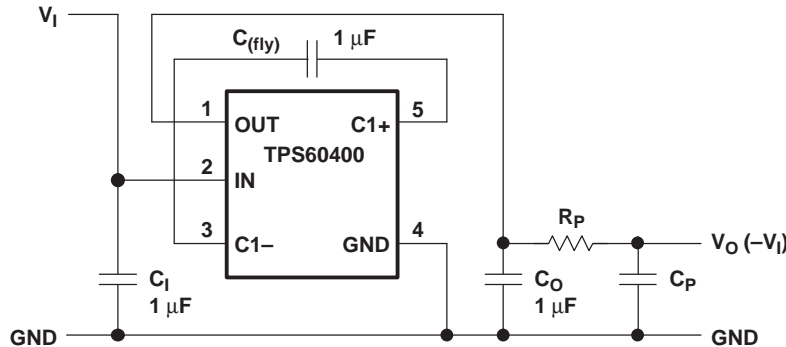


Figure 26. TPS60400 with RC-Post Filter

The equation refers only to the relation between output and input of the ac ripple voltages of the filter.

$$f_c = \frac{1}{2\pi R_P C_P} \quad (1)$$

and ratio V_O/V_{OUT} is:

$$\left| \frac{V_O}{V_{OUT}} \right| = \frac{1}{\sqrt{1 + (2\pi f R_P C_P)^2}} \quad (2)$$

with $R_P = 50 \, \Omega$, $C_P = 0.1 \, \mu F$ and $f = 250 \, \text{kHz}$: $\left| \frac{V_O}{V_{OUT}} \right| = 0.125$ (13)

To reduce the output voltage ripple, a LC post filter can be used.

Figure 27 shows a configuration with a LC-post filter to further reduce output ripple and noise.

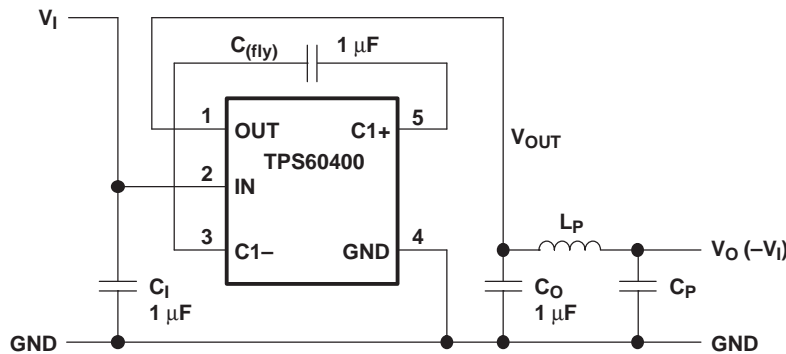


Figure 27. LC-Post Filter

The application allows to generate a voltage rail at a level of 1/2 of the input voltage.

A switched-capacitor voltage inverter can be configured as a high efficiency rail-splitter. This circuit provides a bipolar power supply that is useful in battery powered systems to supply dual-rail ICs, like operational amplifiers. Moreover, the SOT23-5 package and associated components require very little board space.

After power is applied, the flying capacitor (C_{fly}) connects alternately across the output capacitors C_3 and C_O . This equalizes the voltage on those capacitors and draws current from V_I to V_O as required to maintain the output at 1/2 V_I .

System Examples (continued)

The maximum input voltage between V_I and GND in the schematic (or between IN and OUT at the device itself) must not exceed 6.5 V.

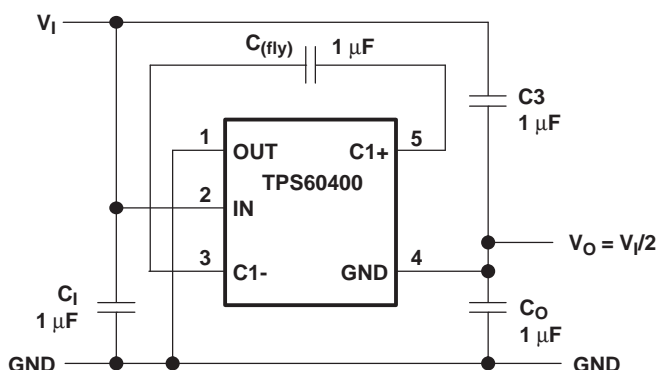


Figure 28. TPS60400 as a High-Efficiency Rail Splitter

The application allows to generate a voltage rail at a level of $-V_I$ as well as $2 \times V_I$ ($V_{(pos)}$).

In the circuit of Figure 29, capacitors C_I , $C_{(fly)}$, and C_O form the inverter, while C_1 and C_2 form the doubler. C_1 and $C_{(fly)}$ are the flying capacitors; C_O and C_2 are the output capacitors. Because both the inverter and doubler use part of the charge-pump circuit, loading either output causes both outputs to decline toward GND. Make sure the sum of the currents drawn from the two outputs does not exceed 60 mA. The maximum output current at $V_{(pos)}$ must not exceed 30 mA. If the negative output is loaded, this current must be further reduced.

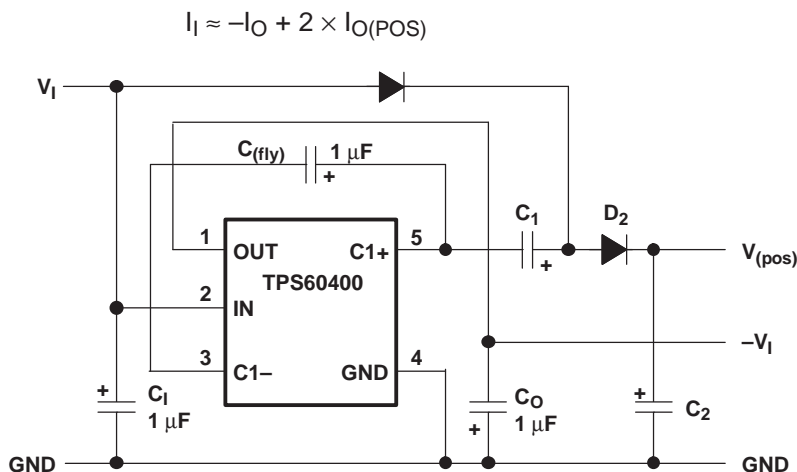


Figure 29. TPS60400 as Doubler/Inverter

The application generate a voltage rail at a level $-2 \times V_I$.

Two devices can be cascaded to produce an even larger negative voltage (see Figure 30). The unloaded output voltage is normally $-2 \times V_I$, but this is reduced slightly by the output resistance of the first device multiplied by the quiescent current of the second. When cascading more than two devices, the output resistance rises dramatically.

System Examples (continued)

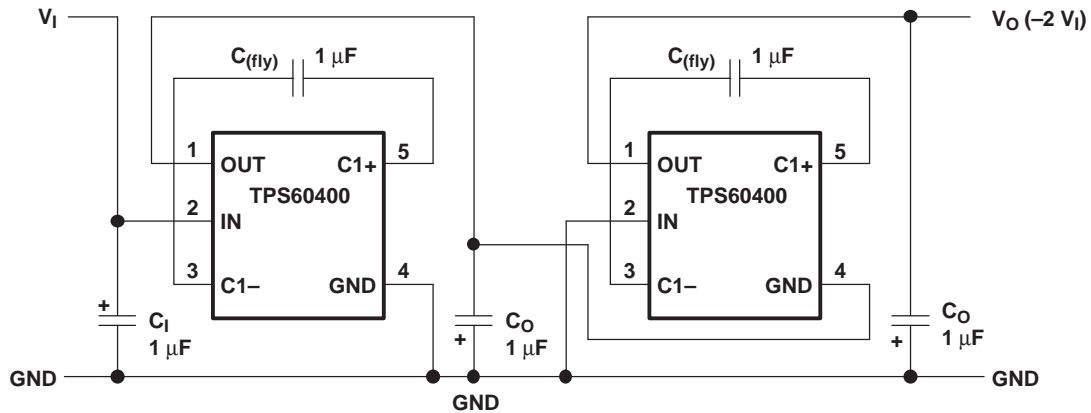


Figure 30. Doubling Inverter

The application allows to increase the output current by using two or more in parallel.

Paralleling multiple TPS6040xs reduces the output resistance. Each device requires its own flying capacitor (C_{fly}), but the output capacitor (C_O) serves all devices (see Figure 31). Increase C_O 's value by a factor of n , where n is the number of parallel devices. Equation 1 shows the equation for calculating output resistance.

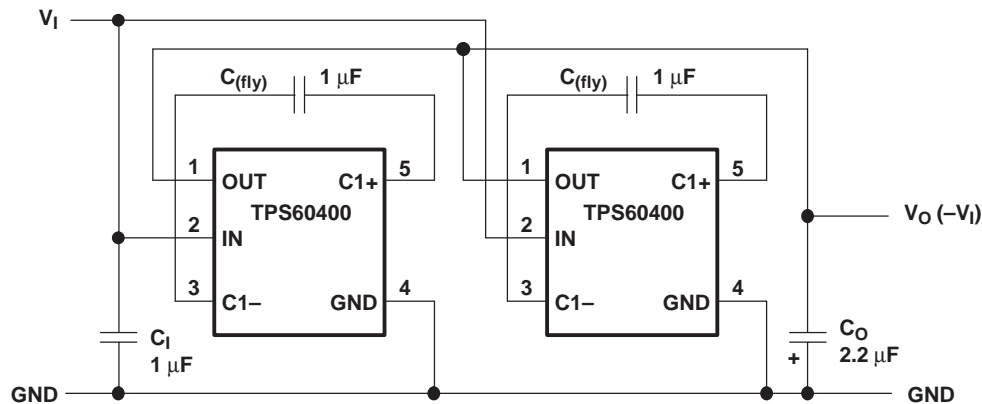


Figure 31. Paralleling Devices

The application adds a shutdown function.

If shutdown is necessary, use the circuit in Figure 32. The output resistance of the TPS6040x typically is 15 Ω plus two times the output resistance of the buffer.

Connecting multiple buffers in parallel reduces the output resistance of the buffer driving the IN pin.

System Examples (continued)

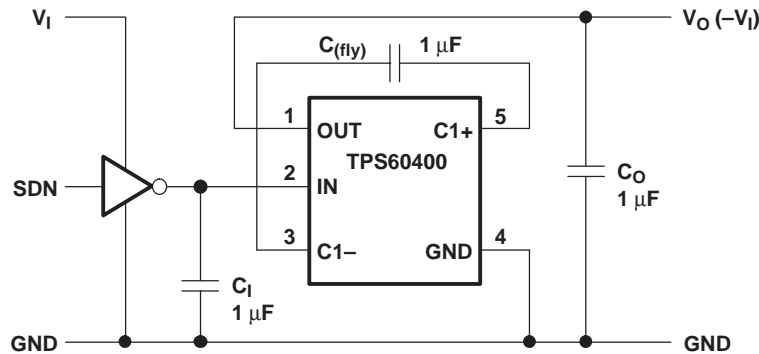


Figure 32. Shutdown Control

The application generates a regulated output voltage for a GaAs bias supply.

A solution for a -2.7-V/3-mA GaAs bias supply is proposed in Figure 33. The input voltage of 3.3 V is first inverted with a TPS60403 and stabilized using a TLV431 low-voltage shunt regulator. Resistor R_P with capacitor C_P is used for filtering the output voltage.

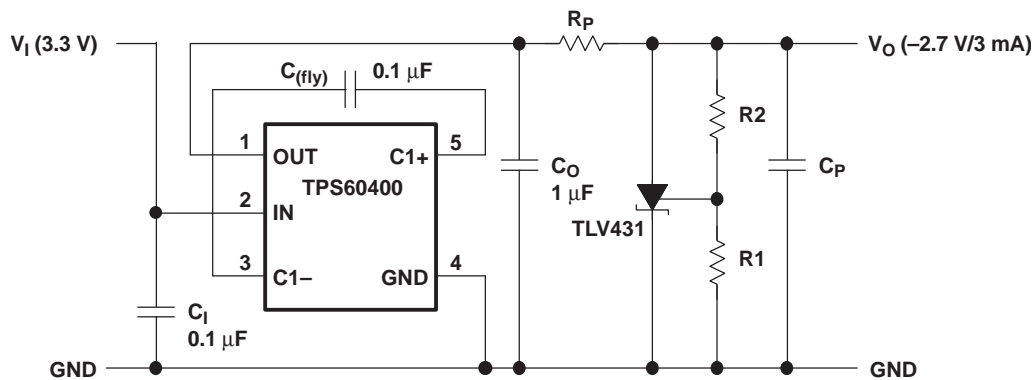


Figure 33. GaAs Supply

A 0.1-μF capacitor was selected for C_{fly} . By this, the output resistance of the inverter is about 52 Ω.

$R_{P_{MAX}}$ can be calculated using the following equation:

$$V_O = - \left(1 + \frac{R_1}{R_2} \right) \times V_{ref} - R_1 \times I_{l(ref)} \quad (14)$$

A 100-Ω resistor was selected for R_P .

The reference voltage across R_2 is 1.24 V typical. With 5-μA current for the voltage divider, R_2 gets:

$$R_{P_{MAX}} = \left(\frac{V_{CO} - V_O}{I_O} - R_O \right)$$

With: $V_{CO} = -3.3$ V; $V_O = -2.7$ V; $I_O = -3$ mA

$R_{P_{MAX}} = 200 \text{ } \Omega - 52 \text{ } \Omega = 148 \text{ } \Omega$

(15)

With $C_P = 1 \text{ } \mu\text{F}$ the ratio V_O/V_I of the RC post filter is:

System Examples (continued)

$$R2 = \frac{1.24 \text{ V}}{5 \mu\text{A}} \approx 250 \text{ k}\Omega$$

$$R1 = \frac{2.7 - 1.24 \text{ V}}{5 \mu\text{A}} \approx 300 \text{ k}\Omega$$

(16)

$$\left| \frac{V_O}{V_I} \right| = \frac{1}{\sqrt{1 + (2\pi 125000 \text{ Hz} \times 100 \Omega \times 1 \mu\text{F})^2}} \approx 0.01$$

(17)

The application generates an output voltage of 1/2 of the input voltage.

By exchanging GND with OUT (connecting the GND pin with OUT and the OUT pin with GND), a step-down charge pump can easily be formed. In the first cycle S1 and S3 are closed, and $C_{(\text{fly})}$ with C_O in series are charged. Assuming the same capacitance, the voltage across $C_{(\text{fly})}$ and C_O is split equally between the capacitors. In the second cycle, S2 and S4 close and both capacitors with $V_I/2$ across are connected in parallel.

The maximum input voltage between V_I and GND in the schematic (or between IN and OUT at the device itself) must not exceed 6.5 V. For input voltages in the range of 6.5 V to 11 V, an additional Zener-diode is recommended (see [Figure 36](#)).

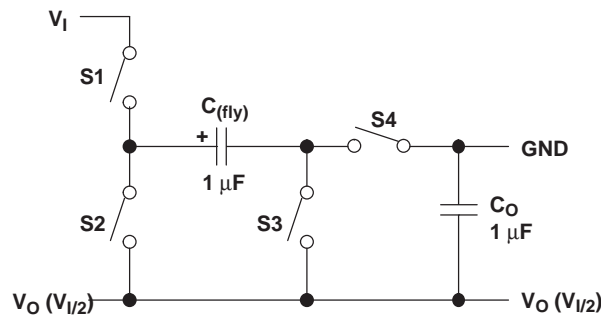


Figure 34. Step-Down Principle

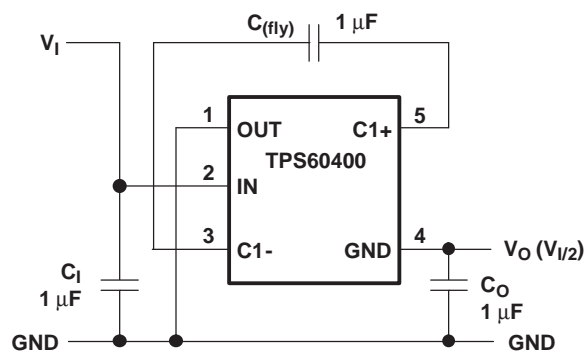


Figure 35. Step-Down Charge Pump Connection

System Examples (continued)

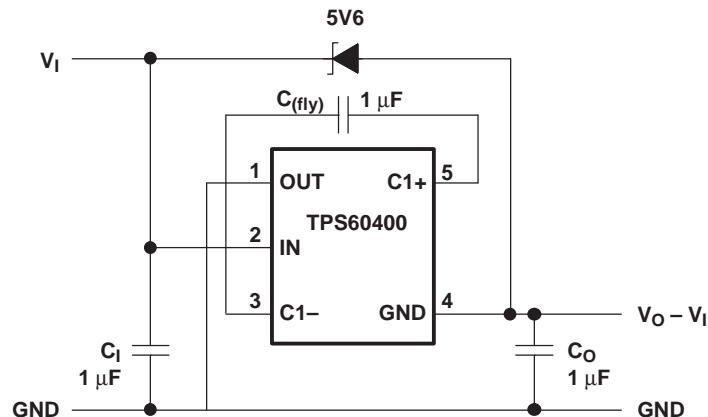


Figure 36. Step-Down Charge Pump Connection for Higher Input Voltages

10 Power Supply Recommendations

The TPS60400 device family has no special requirements for its power supply. The power supply output needs to be rated according to the supply voltage, output voltage and output current of the TPS6040x.

11 Layout

11.1 Layout Guidelines

All capacitors should be soldered as close as possible to the IC. A PCB layout proposal for a single-layer board is shown in [Figure 37](#). Care has been taken to connect all capacitors as close as possible to the circuit to achieve optimized output voltage ripple performance.

11.2 Layout Example

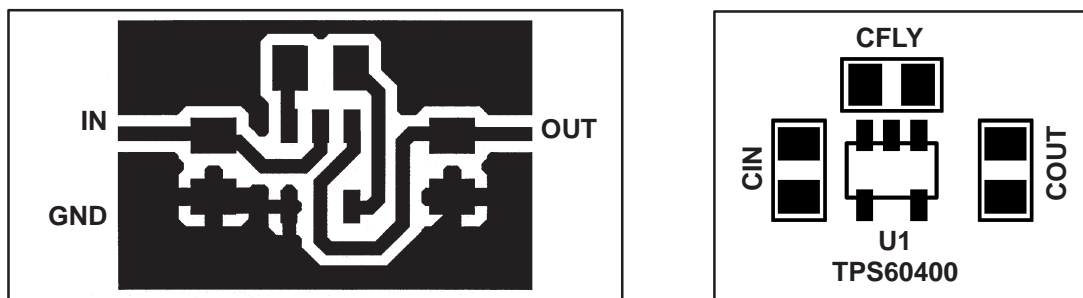


Figure 37. Recommended PCB Layout for TPS6040x (Top Layer)

12 Device and Documentation Support

12.1 Device Support

12.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

12.1.2 Device Family Products

Other inverting DC-DC converters from Texas Instruments are listed in [Table 5](#).

Table 5. Product Identification

| PART NUMBER | DESCRIPTION |
|-------------------------|--|
| TPS6735 | Fixed negative 5-V, 200-mA inverting dc-dc converter |
| TPS6755 | Adjustable 1-W inverting dc-dc converter |

12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 6. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|----------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| TPS60400 | Click here | Click here | Click here | Click here | Click here |
| TPS60401 | Click here | Click here | Click here | Click here | Click here |
| TPS60402 | Click here | Click here | Click here | Click here | Click here |
| TPS60403 | Click here | Click here | Click here | Click here | Click here |

12.3 Trademarks

All trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TPS60400DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFKI | Samples |
| TPS60400DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFKI | Samples |
| TPS60400DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFKI | Samples |
| TPS60400DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFKI | Samples |
| TPS60401DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFLI | Samples |
| TPS60401DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFLI | Samples |
| TPS60401DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFLI | Samples |
| TPS60401DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFLI | Samples |
| TPS60402DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFMI | Samples |
| TPS60402DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFMI | Samples |
| TPS60402DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFMI | Samples |
| TPS60402DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFMI | Samples |
| TPS60403DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFNI | Samples |
| TPS60403DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFNI | Samples |
| TPS60403DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFNI | Samples |
| TPS60403DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | PFNI | Samples |

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS60400, TPS60401, TPS60402, TPS60403 :

- Automotive: [TPS60400-Q1](#), [TPS60401-Q1](#), [TPS60402-Q1](#), [TPS60403-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS60400DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS60400DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS60401DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.3 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS60401DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS60402DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.3 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS60402DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS60403DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS60403DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS60400DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS60400DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS60401DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS60401DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS60402DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS60402DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS60403DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS60403DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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